

LONG-TERM MODULE TESTING AT WYLE LABORATORIES

JET PROPULSION LABORATORY

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Objectives

- **Identify temperature/humidity-bias failure mechanisms in important photovoltaic designs**
 - **Modules in application experiments**
 - **R & D modules**
 - **Commercial modules**
- **Identify synergisms among the module elements**
 - **Cells, encapsulants, interconnects**
 - **Back covers, edge seals**

Wyle Laboratories Module Test Set

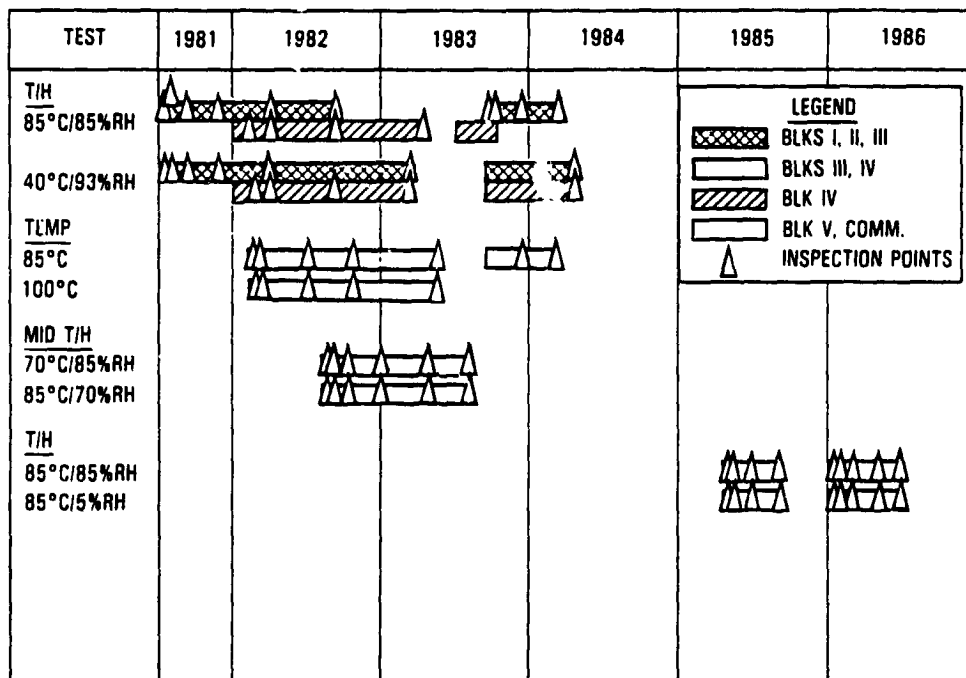
- **Application Experiment Modules**
 - **Arco Solar - SMUD, Phase 1**
 - **Solarex - SMUD, Phase 2**
 - **Mobile Solar - SMUD, Phase 2**
 - **Solarex - Georgetown**
- **R & D Modules**
 - **Westinghouse**
- **Commercial Modules**
 - **Tideland Signal**
 - **Solec**

MODULE AND RELIABILITY TECHNOLOGY

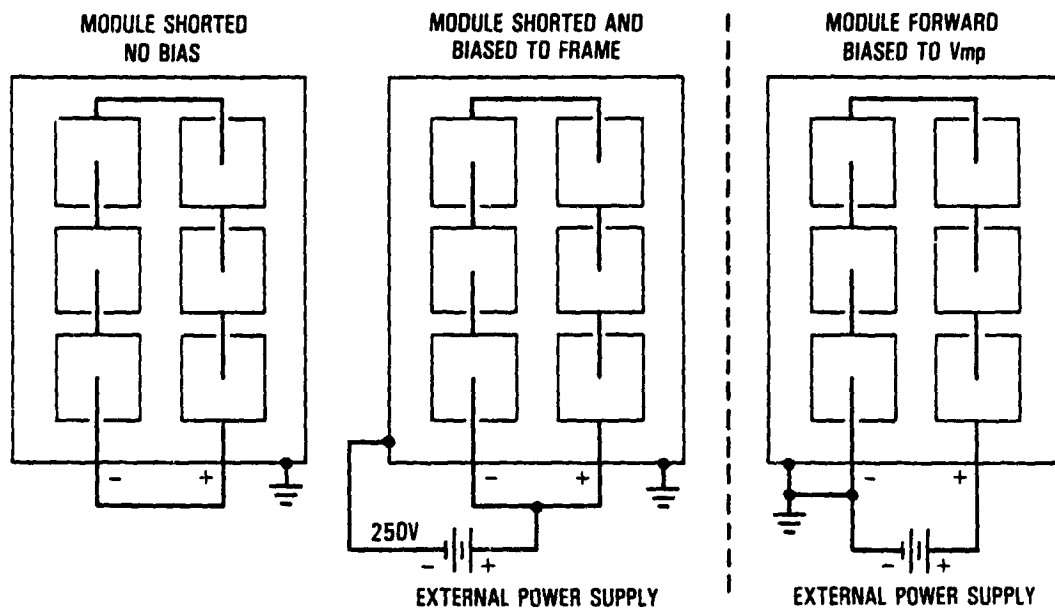
Module Materials

Design Details	Prior Tests	Current Test
Front cover	glass, Tedlar/none	glass
Encapsulants	silicone, PVB, EVA	EVA, APU, silicone
Cell types	CZ (p/n, n/p), semi-Xtl	semi-Xtl, CZ, EFG ribbon, D-web, a-Si
Cell metallization	Ni-Sn, Ti-Pd-Ag, print Ag, Pd-Ni-Sn	Ti-Pd-Cu, print Ag, Ti-Pd-Ag, Ni-Cu-Sn
Back cover	Tedlar, mylar, T-P-T T-Al-T	Tedlar, T-P-T, glass, P-Al-T, T-Al-T, white RTV
Frame	Al, stainless steel	Al, stainless steel
Edge seals	EPDM, RTV, acrylic tape, FRP, PS, butyl, silicone	EPDM, FRP, acrylic tape, mylar tape, none

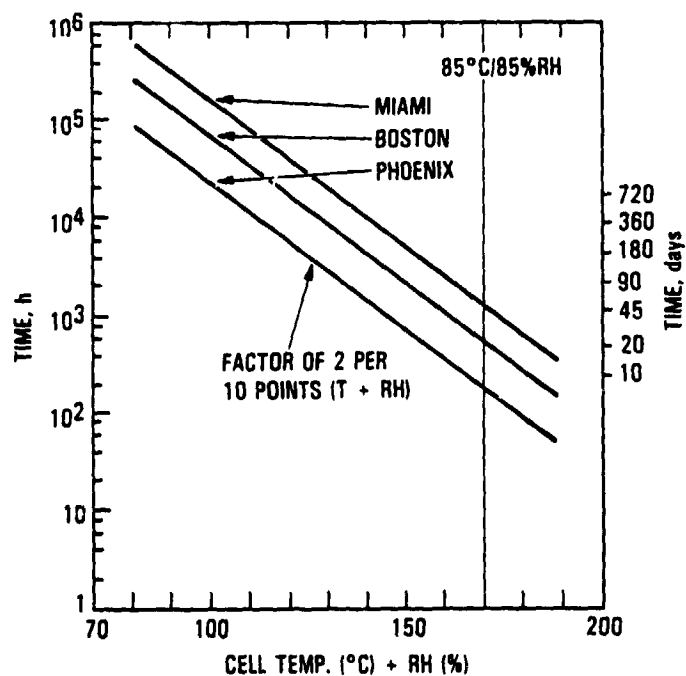
Long-Term Module Testing Schedule at Wyle Laboratories



Wyle Laboratories Voltage-Bias Circuits

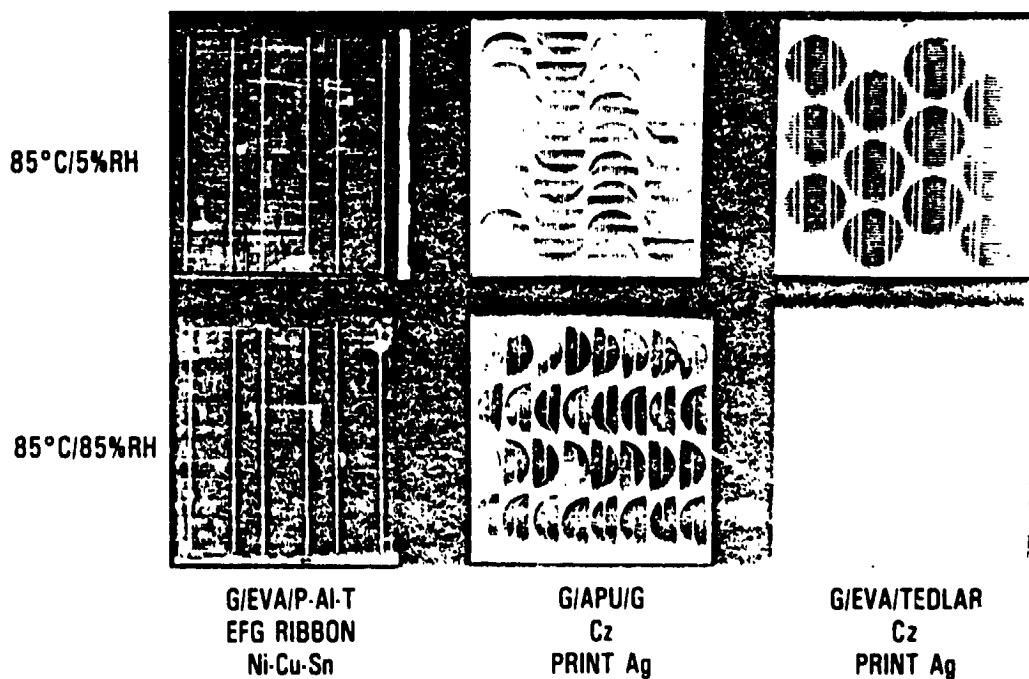
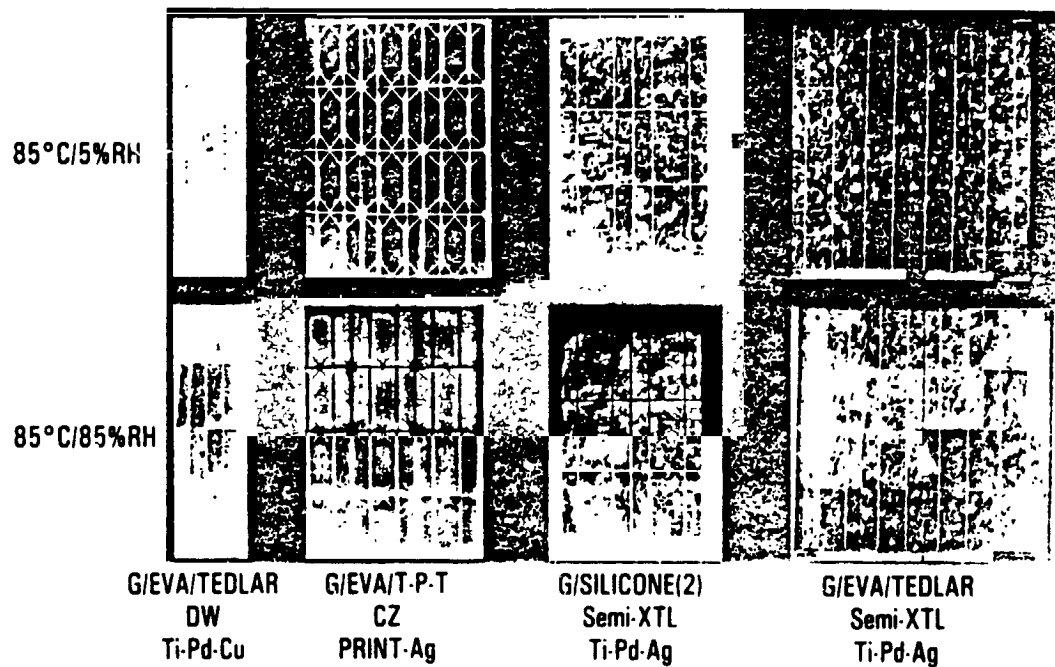


Combined Environment Tests
(Temperature/Humidity Durations Equivalent to a 20-Year Field Exposure)



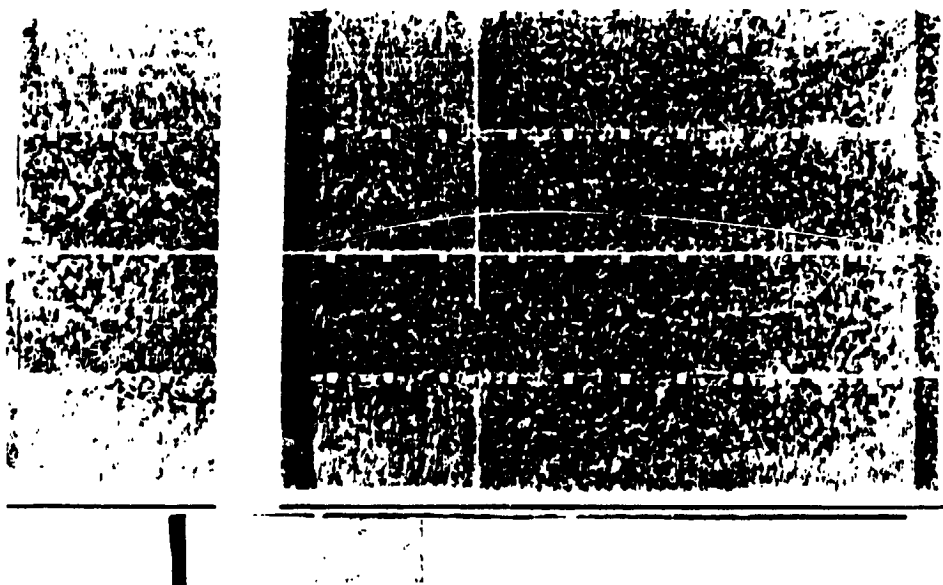
MODULE AND RELIABILITY TECHNOLOGY

Combined Environment Results: Comparison After 40 Days of Various Module Designs



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Electrochemical Degradation of Glass/EVA/Tedlar Module (at Day 40)



Performance Degradation After 40 Days at 85°C/85% RH
(Approximately Equivalent to 20 Years in the Field)

Encapsula	Metallization	P/P ₀ Power Loss	
		Transmissivity	Series Resistance
Glass/EVA/Tedlar	Print-Ag	0.99	0.82
	Ti-Pd-Cu	0.96	1.00
	Ti-Pd-Ag	0.95	0.99
Glass/EVA/T-P-T	Print-Ag	0.96	0.91
Glass/EVA/Foil	Ni-Cu-Sn	0.99	0.99
Glass/APU/Glass	Print-Ag	0.97	0.99
Glass/Silicone	Ti-Pd-Ag	0.99	0.97
Strawman 20-year goal for total degradation in all environments		0.96	0.96

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Conclusions

- A variety of present module types are consistent with 20-year life with respect to typical temperature/humidity site stress
- Degradation mechanisms identified include:
 - Discoloration of encapsulants
 - Electrochemical corrosion of cell metallization
 - Material diffusion from edge seals
 - Delamination (foil), and embrittlement of back covers
- Important to have voltage-bias in qualification tests
- Important to include both temperature/humidity and temperature-only test for identifying degradation mechanisms

